HEF4528B

Dual monostable multivibrator

Rev. 7 — 22 November 2011 Product data sheet

1. General description

The HEF4528B is a dual retriggerable-resetable monostable multivibrator. Each multivibrator has an active LOW input ($n\overline{A}$), and active HIGH input (nB), an active LOW clear direct input ($n\overline{CD}$), an output (nQ) and its complement ($n\overline{Q}$), and two external timing component connecting pins (nCEXT, always connected to ground, and nREXT/CEXT).

An external timing capacitor (C_{EXT}) must be connected between nCEXT and nREXT/CEXT and an external resistor (R_{EXT}) must be connected between nREXT/CEXT and V_{DD}. The output pulse duration is determined by the external timing components C_{EXT} and R_{EXT}. A HIGH-to-LOW transition on $n\overline{A}$ when nB is LOW or a LOW-to-HIGH transition on nB when $n\overline{A}$ is HIGH produces a positive pulse (LOW-HIGH-LOW) on nQ and a negative pulse (HIGH-LOW-HIGH) on $n\overline{Q}$ if the $n\overline{CD}$ is HIGH. A LOW on $n\overline{CD}$ forces nQ LOW, $n\overline{Q}$ HIGH and inhibits any further pulses until $n\overline{CD}$ is HIGH.

It operates over a recommended V_{DD} power supply range of 3 V to 15 V referenced to V_{SS} (usually ground). Unused inputs must be connected to V_{DD}, V_{SS}, or another input.

2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Specified from −40 °C to +85 °C
- Complies with JEDEC standard JESD 13-B

3. Ordering information

Table 1. Ordering information

All types operate from −40 °C to +85 °C.

Type number	Package		
	Name	Description	Version
HEF4528BP	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
HEF4528BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

4. Functional diagram

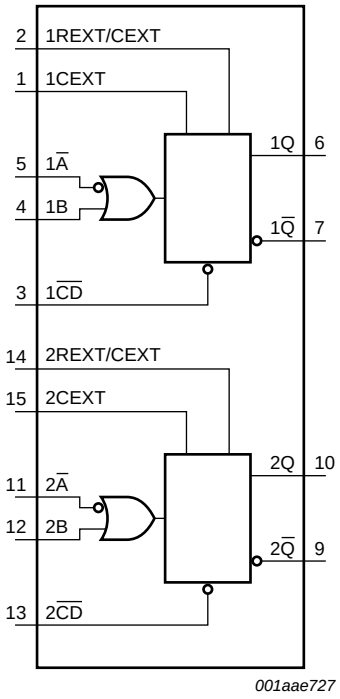


Fig 1. Functional diagram

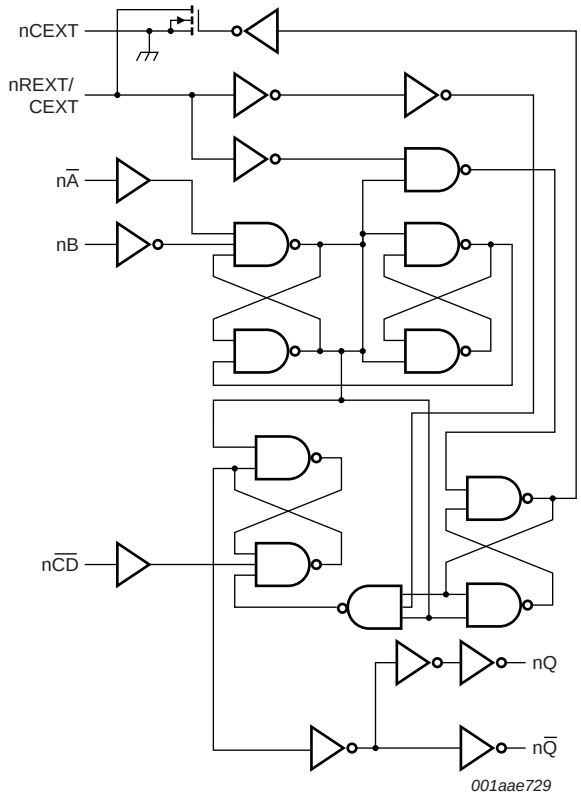


Fig 2. Logic diagram for one monostable multivibrator

5. Pinning information

5.1 Pinning

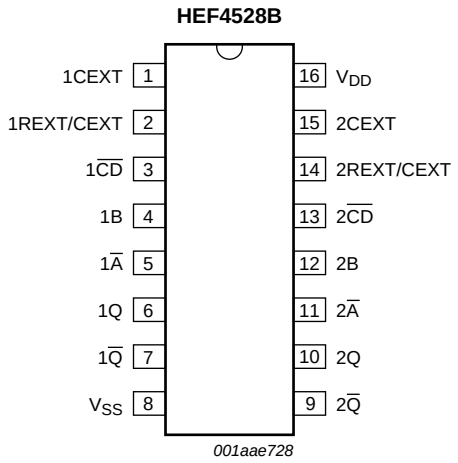


Fig 3. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1CEXT, 2CEXT	1, 15	external capacitor connection (always connected to ground)
1REXT/CEXT, 2REXT/CEXT	2, 14	external capacitor/resistor connection
$1\overline{CD}$, $2\overline{CD}$	3, 13	clear direct input (active LOW)
1B, 2B	4, 12	input (LOW-to-HIGH triggered)
$1\overline{A}$, $2\overline{A}$	5, 11	input (HIGH-to-LOW triggered)
1Q, 2Q	6, 10	output
$1\overline{Q}$, $2\overline{Q}$	7, 9	complementary output (active LOW)
V_{SS}	8	ground supply voltage
V_{DD}	16	supply voltage

6. Functional description

Table 3. Function table[1]

Inputs			Outputs	
$\overline{A}$	B	$\overline{CD}$	Q	$\overline{Q}$
↓	L	H	⊓	⊔
H	↑	H	⊓	⊔
X	X	L	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care;
↑ = positive-going transition; ↓ = negative-going transition;

⊓ = one HIGH level output pulse, with the pule width determined by C_{EXT} and R_{EXT};

⊔ = one LOW level output pulse, with the pulse width determined by C_{EXT} and R_{EXT}.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to V_{SS} = 0 V (ground).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DD}	supply voltage			−0.5	+18	V
I_{IK}	input clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V		-	±10	mA
V_I	input voltage			−0.5	$V_{DD} + 0.5$	V
I_{OK}	output clamping current	$V_I < -0.5$ V or $V_I > V_{DD} + 0.5$ V		-	±10	mA
$I_{I/O}$	input/output current			-	±10	mA
I_{DD}	supply current			-	50	mA
T_{stg}	storage temperature			−65	+150	°C
T_{amb}	ambient temperature			−40	+85	°C
P_{tot}	total power dissipation	T_{amb} = −40 °C to +85 °C				
		DIP16 package	[1]	-	750	mW
		SO16 package	[2]	-	500	mW
P	power dissipation	per output		-	100	mW

[1] For DIP16 package: P_{tot} derates linearly with 12 mW/K above 70 °C.

[2] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DD}	supply voltage		3	-	15	V
V_I	input voltage		0	-	V_{DD}	V
T_{amb}	ambient temperature	in free air	–40	-	+85	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V_{DD} = 5 V	-	-	3.75	µs/V
		V_{DD} = 10 V	-	-	0.5	µs/V
		V_{DD} = 15 V	-	-	0.08	µs/V

9. Static characteristics

Table 6. Static characteristics

V_{SS} = 0 V; V_I = V_{SS} or V_{DD}; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	T_{amb} = –40 °C		T_{amb} = +25 °C		T_{amb} = +85 °C		Unit
				Min	Max	Min	Max	Min	Max	
V_{IH}	HIGH-level input voltage	$\|I_O\|$ < 1 µA	5 V	3.5	-	3.5	-	3.5	-	V
			10 V	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	V
V_{IL}	LOW-level input voltage	$\|I_O\|$ < 1 µA	5 V	-	1.5	-	1.5	-	1.5	V
			10 V	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	V
V_{OH}	HIGH-level output voltage	$\|I_O\|$ < 1 µA	5 V	4.95	-	4.95	-	4.95	-	V
			10 V	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	V
V_{OL}	LOW-level output voltage	$\|I_O\|$ < 1 µA	5 V	-	0.05	-	0.05	-	0.05	V
			10 V	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	V
I_{OH}	HIGH-level output current	V_O = 2.5 V	5 V	-	–1.7	-	–1.4	-	–1.1	mA
		V_O = 4.6 V	5 V	-	–0.52	-	–0.44	-	–0.36	mA
		V_O = 9.5 V	10 V	-	–1.3	-	–1.1	-	–0.9	mA
		V_O = 13.5 V	15 V	-	–3.6	-	–3.0	-	–2.4	mA
I_{OL}	LOW-level output current	V_O = 0.4 V	5 V	0.52	-	0.44	-	0.36	-	mA
		V_O = 0.5 V	10 V	1.3	-	1.1	-	0.9	-	mA
		V_O = 1.5 V	15 V	3.6	-	3.0	-	2.4	-	mA
I_I	input leakage current		15 V	-	±0.3	-	±0.3	-	±1.0	µA
I_{DD}	supply current	all valid input combinations; I_O = 0 A	5 V	-	20	-	20	-	150	µA
			10 V	-	40	-	40	-	300	µA
			15 V	-	80	-	80	-	600	µA
C_I	input capacitance		-	-	-	-	7.5	-	-	pF

10. Dynamic characteristics

Table 7. Dynamic characteristics

V_{SS} = 0 V; T_{amb} = 25 °C; for waveforms see Figure 6; for test circuit see Figure 7; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula[1]	Min	Typ	Max	Unit
t_{PHL}	HIGH to LOW propagation delay	$n\overline{A}$ or nB to $n\overline{Q}$; see Figure 5	5 V	113 ns + (0.55 ns/pF)C_L	-	140	280	ns
			10 V	39 ns + (0.23 ns/pF)C_L	-	50	100	ns
			15 V	27 ns + (0.16 ns/pF)C_L	-	35	70	ns
		$n\overline{CD}$ to nQ; see Figure 5	5 V	78 ns + (0.55 ns/pF)C_L	-	105	210	ns
			10 V	29 ns + (0.23 ns/pF)C_L	-	40	85	ns
			15 V	22 ns + (0.16 ns/pF)C_L	-	30	60	ns
t_{PLH}	LOW to HIGH propagation delay	$n\overline{A}$ or nB to nQ; see Figure 5	5 V	128 ns + (0.55 ns/pF)C_L	-	155	305	ns
			10 V	49 ns + (0.23 ns/pF)C_L	-	60	115	ns
			15 V	32 ns + (0.16 ns/pF)C_L	-	40	80	ns
		$n\overline{CD}$ to $n\overline{Q}$; see Figure 5	5 V	93 ns + (0.55 ns/pF)C_L	-	120	240	ns
			10 V	39 ns + (0.23 ns/pF)C_L	-	50	105	ns
			15 V	27 ns + (0.16 ns/pF)C_L	-	35	70	ns
t_t	transition time	nQ, $n\overline{Q}$; see Figure 5	5 V [2]	10 ns + (1.00 ns/pF)C_L	-	60	120	ns
			10 V	9 ns + (0.42 ns/pF)C_L	-	30	60	ns
			15 V	6 ns + (0.28 ns/pF)C_L	-	20	40	ns
t_{rec}	recovery time	$n\overline{CD}$ to $n\overline{A}$ or nB; see Figure 6	5 V		0	−75	-	ns
			10 V		0	−30	-	ns
			15 V		0	−25	-	ns
t_{su}	set-up time	$n\overline{CD}$ to $n\overline{A}$ or nB; see Figure 6	5 V		0	−105	-	ns
			10 V		0	−40	-	ns
			15 V		0	−25	-	ns
t_W	pulse width	$n\overline{A}$ LOW; minimum width; see Figure 6	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
		nB HIGH; minimum width; see Figure 6	5 V		50	25	-	ns
			10 V		30	15	-	ns
			15 V		20	10	-	ns
		$n\overline{CD}$ LOW; minimum width; see Figure 6	5 V		60	30	-	ns
			10 V		35	15	-	ns
			15 V		25	10	-	ns
		nQ or $n\overline{Q}$; R_{EXT} = 5 kΩ; C_{EXT} = 15 pF; see Figure 6	5 V [3]		-	235	-	ns
			10 V		-	155	-	ns
			15 V		-	140	-	ns
		nQ or $n\overline{Q}$; R_{EXT} = 10 kΩ; C_{EXT} = 1 nF; see Figure 6	5 V [4]		-	5.45	-	µs
			10 V		-	4.95	-	µs
			15 V		-	4.85	-	µs

Table 7. Dynamic characteristics *...continued*

V_{SS} = 0 V; T_{amb} = 25 °C; for waveforms see Figure 6; for test circuit see Figure 7; unless otherwise specified.

Symbol	Parameter	Conditions	V_{DD}	Extrapolation formula[1]	Min	Typ	Max	Unit
Δt_W	pulse width variation	nQ output variation over temperature range	5 V	[5]	-	±3	-	%
			10 V		-	±2	-	%
			15 V		-	±2	-	%
		nQ output variation over voltage range V_{DD} ± 5 %	5 V		-	±2	-	%
			10 V		-	±1	-	%
			15 V		-	±1	-	%
R_{EXT}	external timing resistor	see Figure 4	5 V		5	-	2	MΩ
			10 V		5	-	2	MΩ
			15 V		5	-	2	MΩ
C_{EXT}	external timing capacitor	see Figure 4	5 V		no limits			
			10 V		no limits			
			15 V		no limits			

[1] The typical values of the propagation delay and transition times are calculated from the extrapolation formulas shown (C_L in pF).

[2] t_t is the same as t_{THL} and t_{TLH}.

[3] For other R_{EXT}, C_{EXT} combinations and C_{EXT} < 0.01 µF see Figure 4.

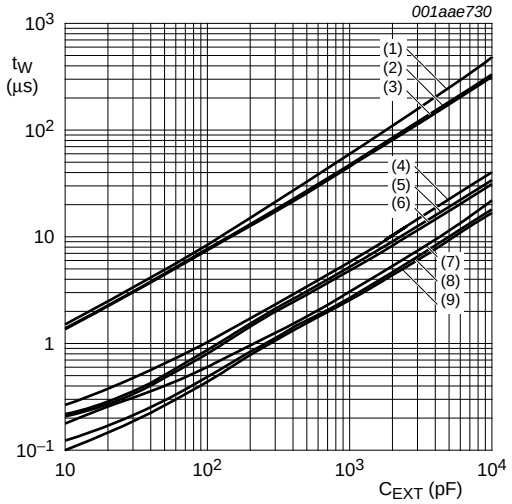
[4] For other R_{EXT}, C_{EXT} combinations and C_{EXT} > 0.01 µF use formula $t_W = K \times R_{EXT} \times C_{EXT}$.
where: t_W = output pulse width (s);
R_{EXT} = external timing resistor (Ω);
C_{EXT} = external timing capacitor (F);
K = 0.42 for V_{DD} = 5 V;
K = 0.32 for V_{DD} = 10 V;
K = 0.30 for V_{DD} = 15 V.

[5] T_{amb} = −40 °C to +85 °C; Δt_W is referenced to t_W at T_{amb} = 25 °C.

Table 8. Dynamic power dissipation P_D

P_D can be calculated from the formulas shown. V_{SS} = 0 V; $t_r = t_f \leq 20$ ns; T_{amb} = 25 °C.

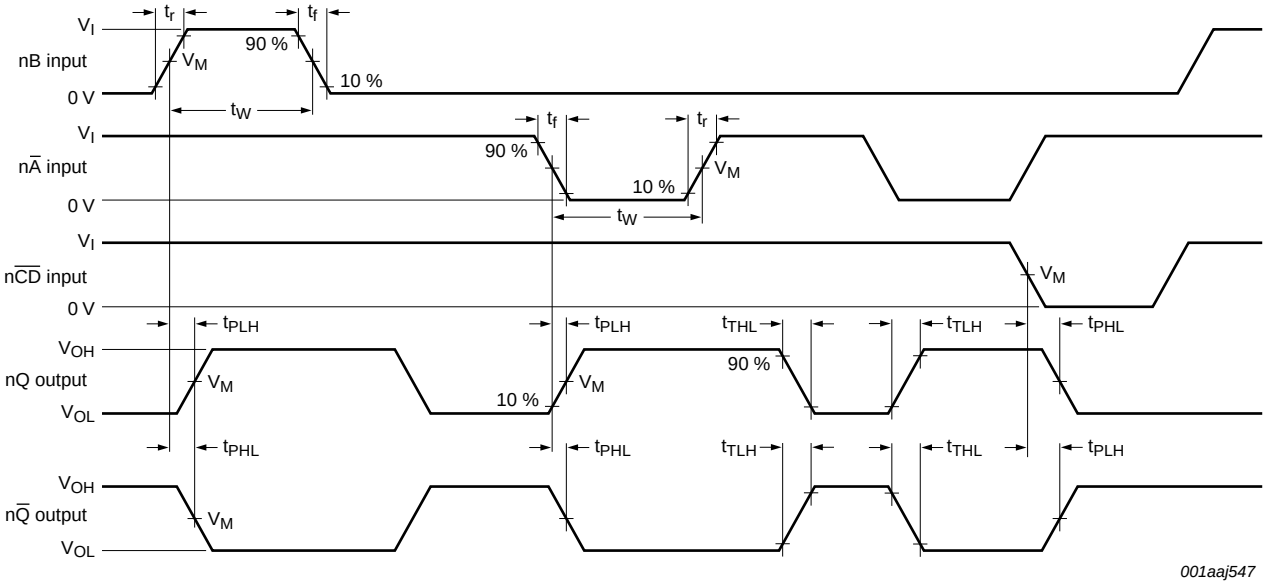
Symbol	Parameter	V_{DD}	Typical formula for P_D (µW)	where:
P_D	dynamic power dissipation	5 V	$P_D = 4000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f_i = input frequency in MHz;
		10 V	$P_D = 20000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	f_o = output frequency in MHz;
		15 V	$P_D = 59000 \times f_i + \Sigma(f_o \times C_L) \times V_{DD}^2$	C_L = output load capacitance in pF;
				V_{DD} = supply voltage in V;
				$\Sigma(f_o \times C_L)$ = sum of the outputs.



(1) R_{EXT} = 100 kΩ, V_{DD} = 5 V.
(2) R_{EXT} = 100 kΩ, V_{DD} = 10 V.
(3) R_{EXT} = 100 kΩ, V_{DD} = 15 V.
(4) R_{EXT} = 10 kΩ, V_{DD} = 5 V.
(5) R_{EXT} = 10 kΩ, V_{DD} = 10 V.
(6) R_{EXT} = 10 kΩ, V_{DD} = 15 V.
(7) R_{EXT} = 5 kΩ, V_{DD} = 5 V.
(8) R_{EXT} = 5 kΩ, V_{DD} = 10 V.
(9) R_{EXT} = 5 kΩ, V_{DD} = 15 V.

Fig 4. Output pulse width (t_W) as a function of external timing capacitor (C_{EXT})

11. Waveforms



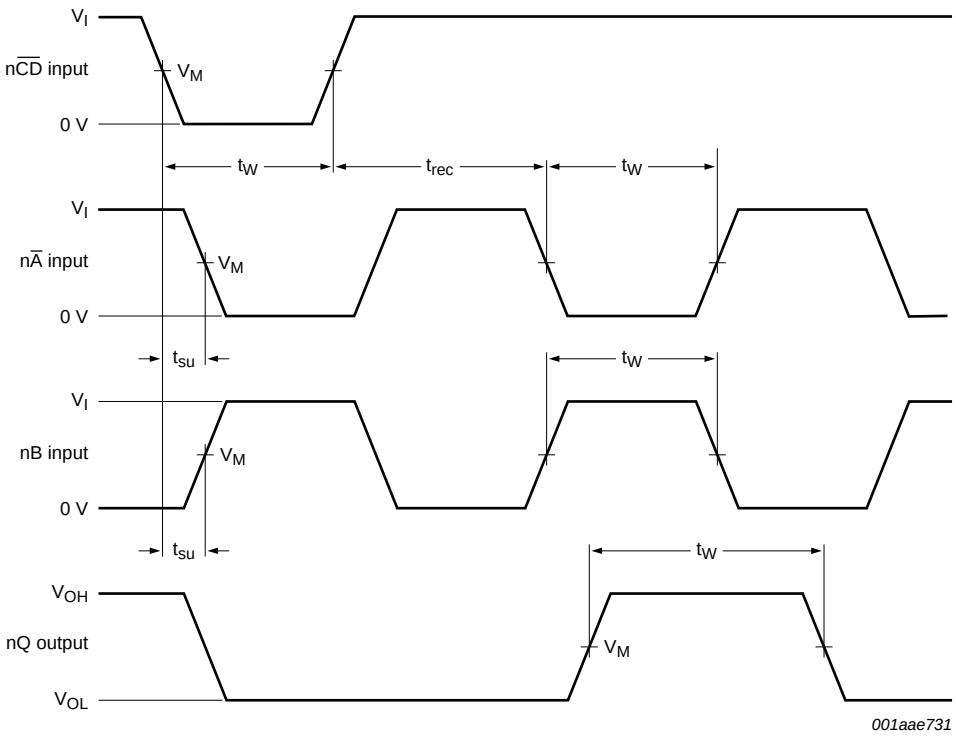
Measurement points are given in Table 9.

Logic levels: V_{OL} and V_{OH} are typical output levels that occur with the output load.

Fig 5. Waveforms showing propagation delays and transition times

Table 9. Measurement points

Supply voltage	Input	Output
V_{DD}	V_M	V_M
5 V to 15 V	$0.5V_{DD}$	$0.5V_{DD}$

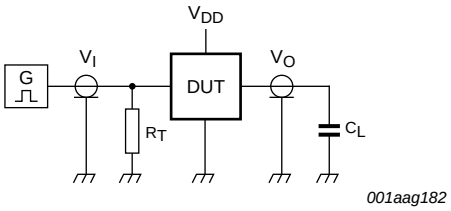


Measurement points are given in Table 9.

Set-up and recovery times are shown as positive values but may be specified as negative values.

Logic levels: V_{OL} and V_{OH} are typical output levels that occur with the output load.

Fig 6. Waveforms showing minimum $n\overline{A}$, nB, and nQ pulse widths and set-up and recovery times



Test data is given in Table 10.

Definitions for test circuit:

DUT = Device Under Test.

C_L = load capacitance including jig and probe capacitance.

R_T = termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig 7. Test circuit for measuring switching times

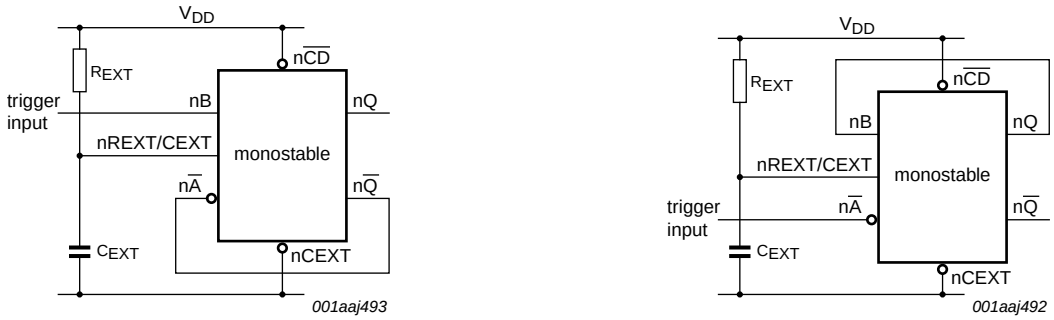
Table 10. Test data

Supply voltage	Input		Load
V_{DD}	V_I	t_r, t_f	C_L
5 V to 15 V	V_{SS} or V_{DD}	≤ 20 ns	50 pF

12. Application information

An example of a HEF4528B application is:

- Non-retriggerable monostable multivibrator



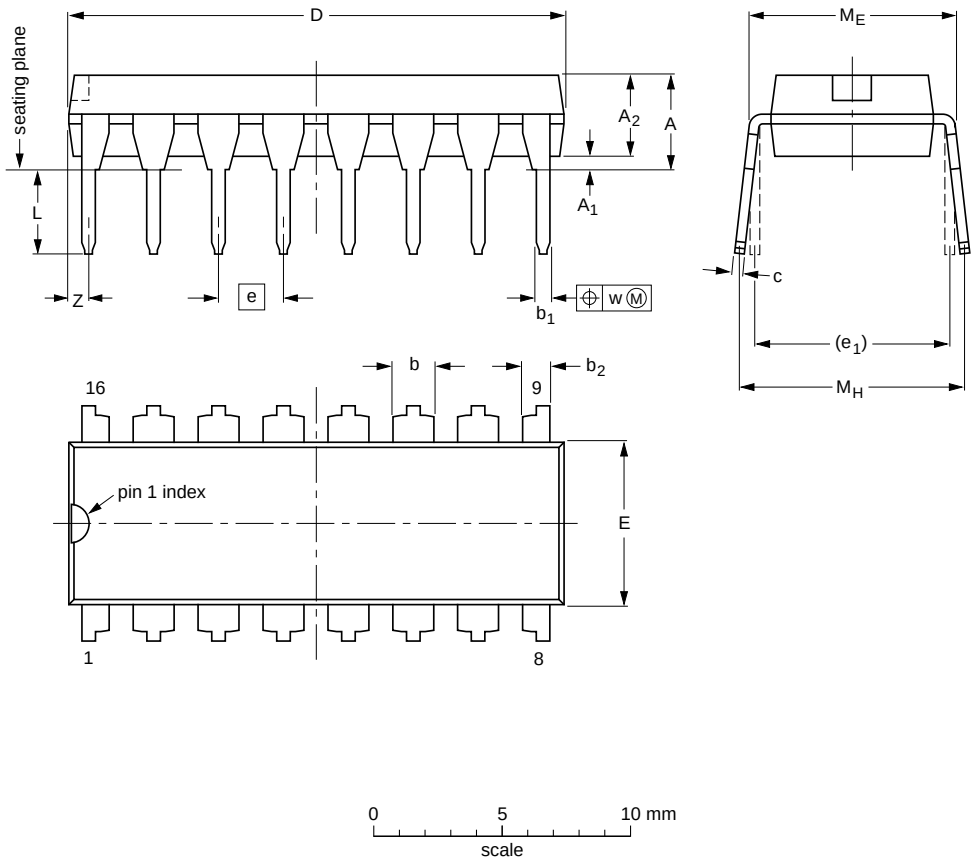
a. Rising edge triggered

b. Falling edge triggered

Fig 8. Non-retriggerable applications

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil) **SOT38-4**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1 min.	A_2 max.	b	b_1	b_2	c	D (1)	E (1)	e	e_1	L	M_E	M_H	w	Z (1) max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.02	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.03

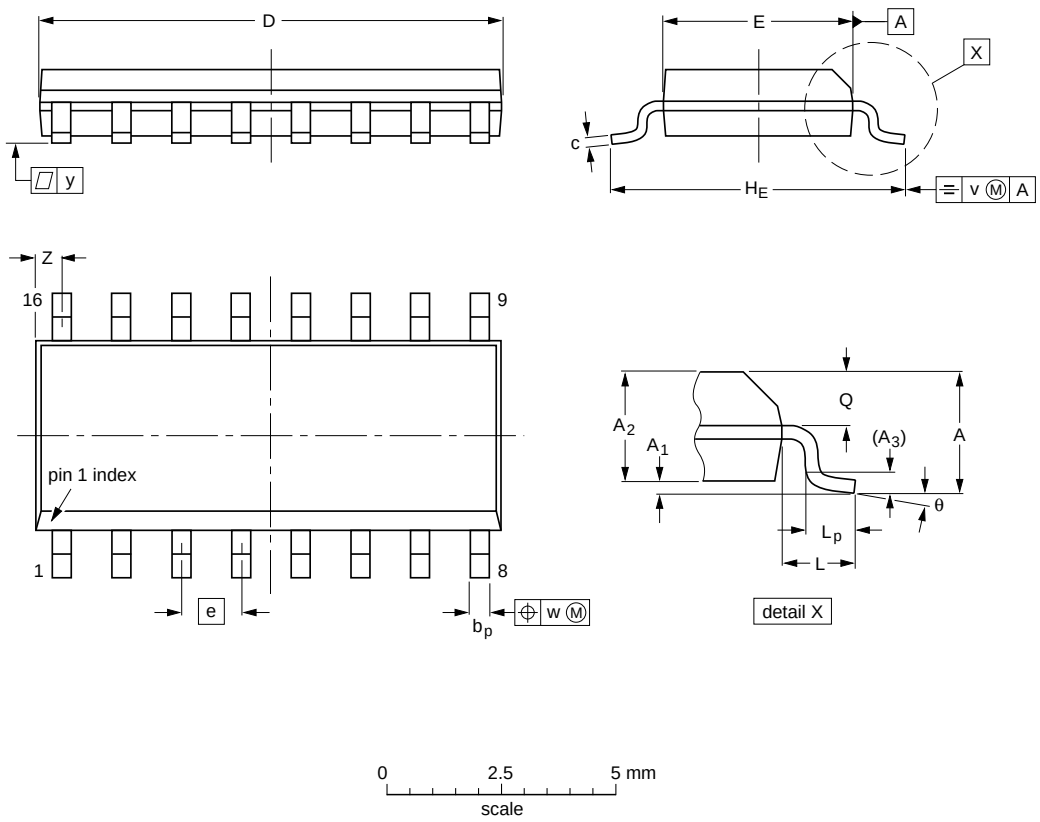
Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT38-4						~~95-01-14~~ 03-02-13

Fig 9. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm **SOT109-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				~~99-12-27~~ 03-02-19

Fig 10. Package outline SOT109-1 (SO16)

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4528B v.7	20111122	Product data sheet	-	HEF4528B v.6
Modifications:	• Section Applications removed • Table 6: I_{OH} minimum values changed to maximum			
HEF4528B v.6	20091127	Product data sheet	-	HEF4528B v.5
HEF4528B v.5	20090813	Product data sheet	-	HEF4528B v.4
HEF4528B v.4	20090209	Product data sheet	-	HEF4528B_CNV v.3
HEF4528B_CNV v.3	19950101	Product specification	-	HEF4528B_CNV v.2
HEF4528B_CNV v.2	19950101	Product specification	-	-

15. Legal information

15.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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